

#### FEATURES :

- LOW INTERMODULATION DISTORTION  
IM<sub>3</sub> = -45 dBc at P<sub>o</sub> = 31.5 dBm,  
Single Carrier Level
- HIGH GAIN  
G<sub>1dB</sub> = 8.0 dB at 5.9 GHz to 6.4 GHz
- HIGH POWER  
P<sub>1dB</sub> = 42.5 dBm at 5.9 GHz to 6.4 GHz
- BROAD BAND INTERNALLY MATCHED
- HERMETICALLY SEALED PACKAGE

#### RF PERFORMANCE SPECIFICATIONS (Ta = 25°C)

| CHARACTERISTICS                        | SYMBOL           | CONDITION   | UNIT | MIN. | TYP. | MAX. |
|--|------------------|---|------|------|------|------|
| Output Power at 1 dB Compression Point | P <sub>1dB</sub> | V <sub>DS</sub> = 10 V<br>f = 5.9~6.4 GHz                 | dBm  | 41.5 | 42.5 | —    |
| Power Gain at 1 dB Compression Point   | G <sub>1dB</sub> |   | dB   | 7.0  | 8.0  | —    |
| Drain Current                          | I <sub>DS</sub>  |   | A    | —    | 4.4  | 5.0  |
| Gain Flatness                          | ΔG               |   | dB   | —    | —    | ±0.8 |
| Power Added Efficiency                 | η <sub>add</sub> |   | %    | —    | 34   | —    |
| 3rd Order Intermodulation Distortion   | IM <sub>3</sub>  | Note 1  | dBc  | -42  | -45  | —    |
| Channel-Temperature Rise               | ΔT <sub>ch</sub> | V <sub>DS</sub> × I <sub>DS</sub> × R <sub>th</sub> (c-c) | °C   | —    | —    | 80   |

#### ELECTRICAL CHARACTERISTICS (Ta = 25°C)

| CHARACTERISTICS               | SYMBOL                | CONDITION  | UNIT | MIN. | TYP. | MAX. |
|-------------------------------|-----------------------|--|------|------|------|------|
| Transconductance              | gm                    | V <sub>DS</sub> = 3 V<br>I <sub>DS</sub> = 6.0 A | mS   | —    | 3600 | —    |
| Pinch-off Voltage             | V <sub>GSoFF</sub>    | V <sub>DS</sub> = 3 V<br>I <sub>DS</sub> = 60 mA | V    | -1   | -2.5 | -4.0 |
| Saturated Drain Current       | I <sub>DSS</sub>      | V <sub>DS</sub> = 3 V<br>V <sub>GS</sub> = 0 V   | A    | —    | 10.5 | 14.0 |
| Gate-Source Breakdown Voltage | V <sub>GSO</sub>      | I <sub>GS</sub> = -200 μA                        | V    | -5   | —    | —    |
| Thermal Resistance            | R <sub>th</sub> (c-c) | Channel to Case                                  | °C/W | —    | 1.5  | 2.0  |

Note 1 : 2 tone Test Pout = 31.5 dBm Single Carrier Level.

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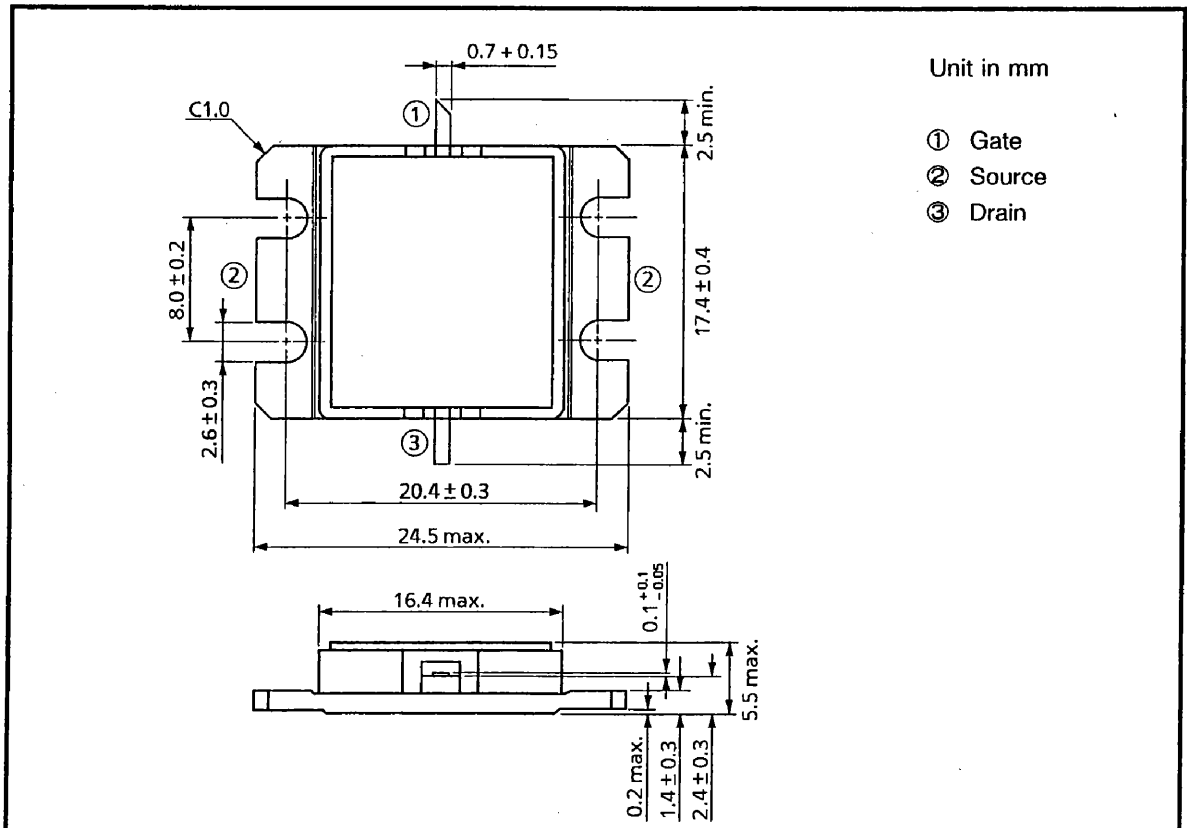


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## ABSOLUTE MAXIMUM RATINGS (Ta = 25°C)

| CHARACTERISTICS                                 | SYMBOL           | UNIT | RATING  |
|---|------------------|------|---------|
| Drain-Source Voltage                            | V <sub>DS</sub>  | V    | 15      |
| Gate-Source Voltage                             | V <sub>GS</sub>  | V    | -5      |
| Drain Current                                   | I <sub>DS</sub>  | A    | 14      |
| Total Power Dissipation (T <sub>C</sub> = 25°C) | P <sub>T</sub>   | W    | 75      |
| Channel Temperature                             | T <sub>ch</sub>  | °C   | 175     |
| Storage Temperature                             | T <sub>stg</sub> | °C   | -65~175 |

## PACKAGE OUTLINE (2-16G1B)

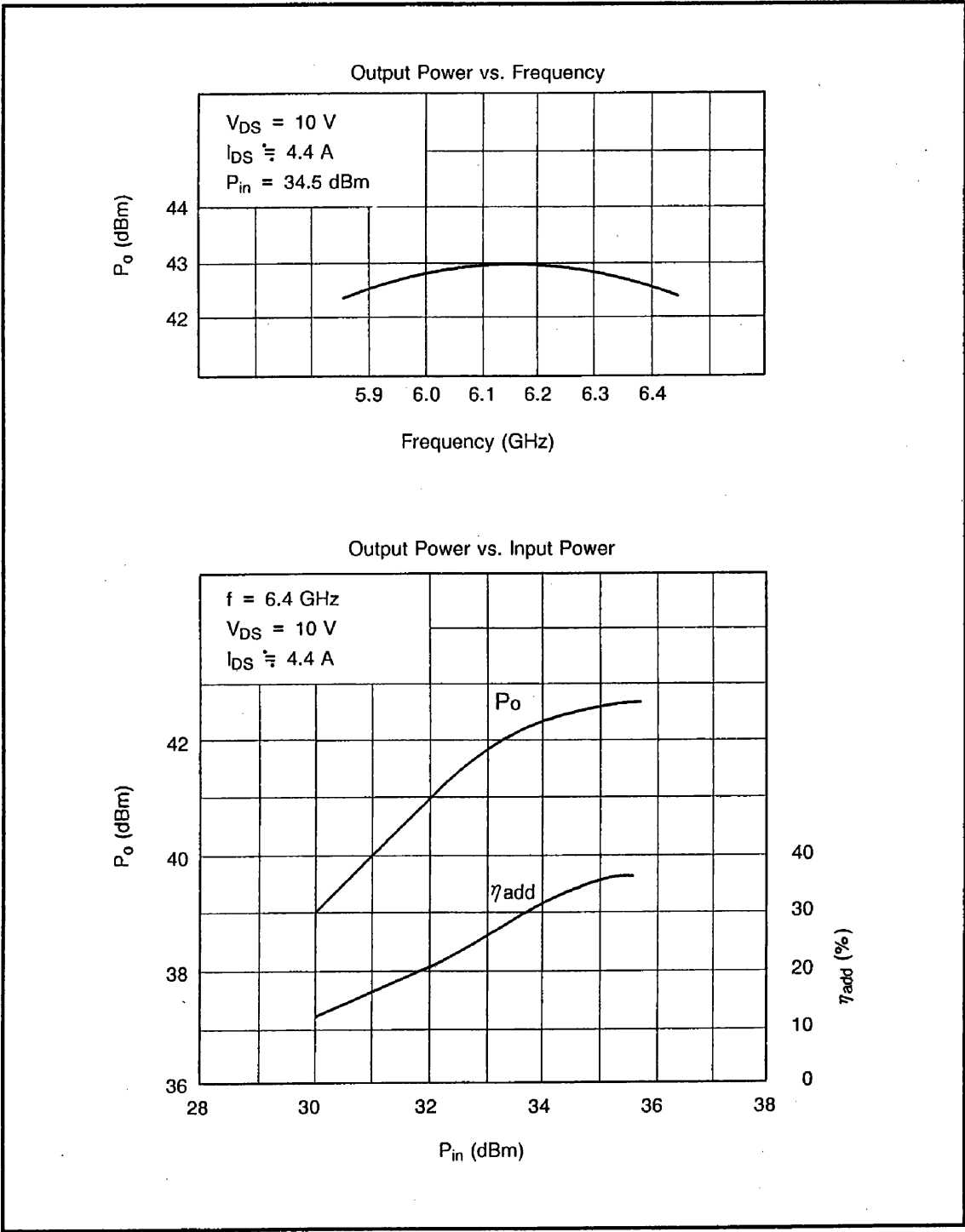


### HANDLING PRECAUTIONS FOR PACKAGED TYPE

Soldering iron should be grounded and the operating time should not exceed 10 seconds at 260°C.

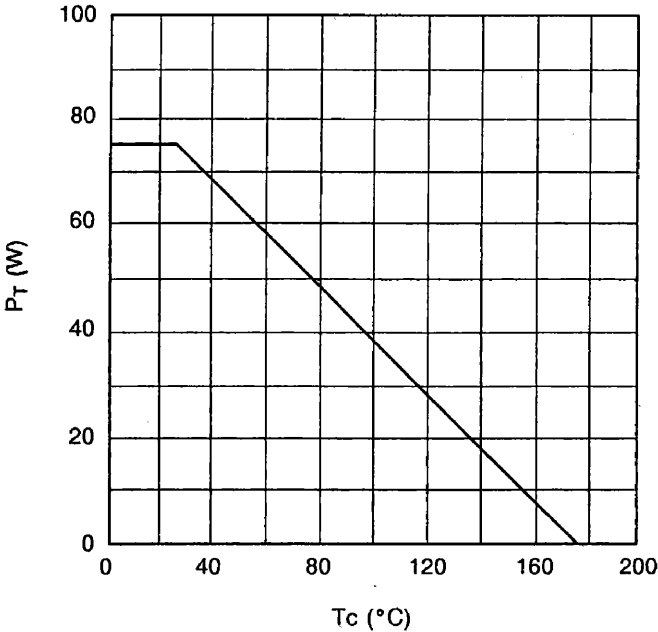
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## RF PERFORMANCES

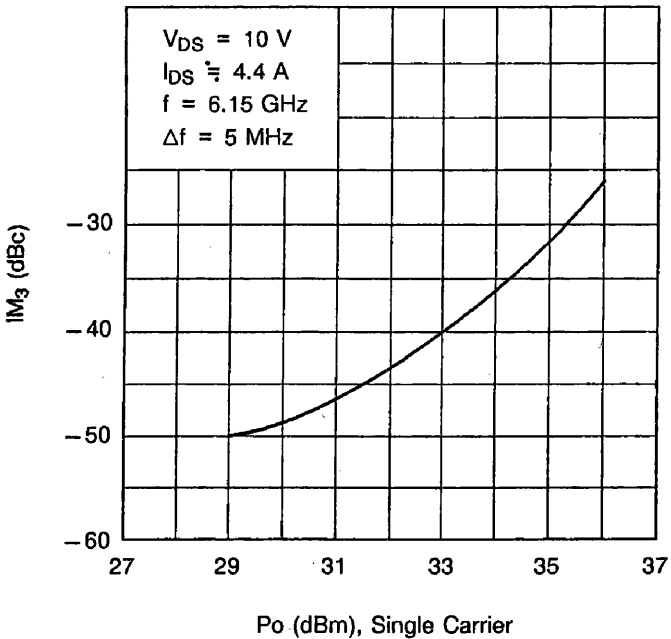


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## POWER DISSIPATION VS. CASE TEMPERATURE



## IM3 VS. OUTPUT POWER CHARACTERISTICS



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## TIM5964-16SL S-PARAMETERS (MAGN. and ANGLES)

V<sub>ds</sub> = 10V , I<sub>ds</sub> = 4.0A

